



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-05-22
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STB55NF06T4	T2EN*ED6EB62	A	SH1A	2017-05-22
Amount		UoM	Unit type	ST ECOPACK Grade
1380.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.20,9.15,4.5	2	gull wing	
Comment	Package: D2PAK WITH TAB CUT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-12th January 2017				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	T2EN*ED6E6Z					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	6.106	mg	supplier	die	Silicon (Si)	7440-21-3		5.911	mg	968064	4283
				supplier	metallization	Aluminium (Al)	7429-90-5		0.113	mg	18506	82
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.031	mg	5077	22
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	492	2
				supplier	back side metallization	Gold (Au)	7440-57-5		0.008	mg	1310	6
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.04	mg	6551	29
Leadframe	Copper & its alloys	792.136	mg	supplier	alloy	Copper (Cu)	7440-50-8		788.289	mg	995144	571224
				supplier	alloy	Iron (Fe)	7439-89-6		0.363	mg	458	263
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.663	mg	837	480
				supplier	metallization	Nickel (Ni)	7440-02-0		2.804	mg	3540	2032
				supplier	metallization	Phosphorus (P)	12185-10-3		0.017	mg	21	12
				supplier	alloy	Lead (Pb)	7439-92-1	7a-Lead in high me	4.412	mg	954978	3197
Soft solder	Solder	4.62	mg	JIG R	solder	Silver (Ag)	7440-22-4		0.116	mg	25108	84
				supplier	solder	Tin (Sn)	7440-31-5		0.092	mg	19914	67
				supplier	wire	Aluminium (Al)	7429-90-5		3.543	mg	999718	2567
Encapsulation	Other Organic Materials	571.105	mg	supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	282	1
				supplier	mold compound	Epoxy Resin	25068-38-6		17.133	mg	30000	12415
				supplier	mold compound	2,2'-(3,3',5,5'-tetramethyl-1,1'-biphenyl)-4,4'	EC 413-900-7		22.844	mg	40000	16554
				supplier	mold compound	phenol resin	29690-82-2		28.556	mg	50001	20693
				supplier	mold compound	Silica, vitreous	60676-86-0		499.716	mg	874998	362113
				supplier	mold compound	Carbon black	1333-86-4		2.856	mg	5001	2070
Connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804